

APPLICATION DATA SHEET**Inventor Information**

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Application Information

Title : SEMICONDUCTOR PACKAGE ASSEMBLY AND
METHOD FOR ELECTRICALLY ISOLATING MODULES
Total Drawing Sheets : 3
Formal Drawings : YES
Application Type : Utility
Attorney Docket Number : 30022/US/3
Assigned : Yes (Large Entity)

Representative Information

Representative Customer No. : 27,076

Continuity Information

This application is a : divisional of
>Application One : 10/057,205
Filing Date : January 25, 2002

Prior Foreign Application

Foreign Application One : 0126821.8
Filing Date : November 7, 2001
Country : United Kingdom
Priority Claimed : Yes

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